

## 25V N-CHANNEL Enhancement Mode MOSFET

### Equivalent Circuit

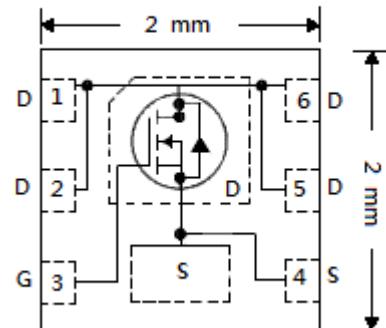
#### Features:

- Low on-resistance
- Excellent thermal and electrical capabilities
- Pb-free lead plating and halogen-free package

BV <sub>DSS</sub>	25V
I <sub>D</sub> @V <sub>GS</sub> =10V, T <sub>C</sub> =25°C	18.2A
I <sub>D</sub> @V <sub>GS</sub> =10V, T <sub>A</sub> =25°C	8.8A
R <sub>DSON</sub> @V <sub>GS</sub> =10V, I <sub>D</sub> =8.5A	10.9mΩ (typ.)
R <sub>DSON</sub> @V <sub>GS</sub> =4.5V, I <sub>D</sub> =6.8A	15.3mΩ (typ.)

**KWB010N02DFJ6**

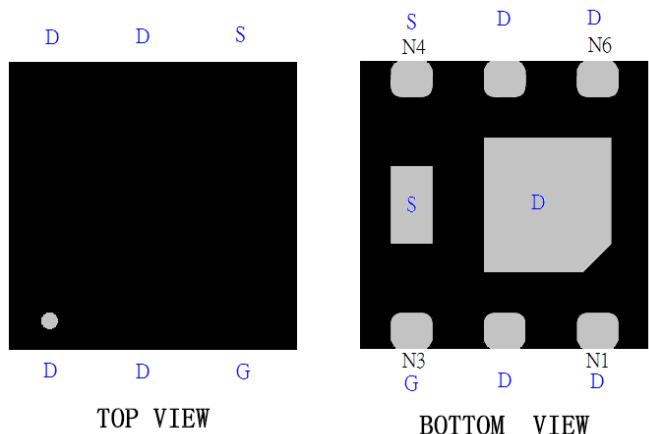
### Top View



G : Gate S : Source D : Drain

### Outline

DFNWB2x2-6L-J



### Ordering Information

Device	Package	Shipping
KWB010N02DFJ6	DFNWB2x2-6L-J (Pb-free lead plating and halogen-free package)	3000 pcs / tape & reel



## Absolute Maximum Ratings ( $T_a=25^\circ C$ )

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	$V_{DS}$	25	V
Gate-Source Voltage	$V_{GS}$	+20	
Continuous Drain Current @ $T_A=25^\circ C$ , $V_{GS}=10V$ (Note 3)	$I_{DSM}$	8.8	A
Continuous Drain Current @ $T_A=70^\circ C$ , $V_{GS}=10V$ (Note 3)		7.0	
Continuous Drain Current @ $T_c=25^\circ C$ , $V_{GS}=10V$	$I_D$	18.2	
Continuous Drain Current @ $T_c=70^\circ C$ , $V_{GS}=10V$		14.6	
Pulsed Drain Current (Note 1, 2)	$I_{DM}$	72	W
Power Dissipation @ $T_A=25^\circ C$ (Note 3)	$P_{DSM}$	2.1	
Power Dissipation @ $T_A=70^\circ C$ (Note 3)		1.3	
Power Dissipation @ $T_c=25^\circ C$	$P_D$	8.9	
Power Dissipation @ $T_c=70^\circ C$		5.7	
Operating Junction and Storage Temperature	$T_j, T_{stg}$	-55~+150	°C

## Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{th,j-c}$	14	°C/W
Thermal Resistance, Junction-to-ambient, max	$R_{th,j-a}$	60 (Note 3)	

Note : 1. Pulse width limited by maximum junction temperature  
 2. Duty cycle≤1%  
 3. Surface mounted on 1 in<sup>2</sup>copper pad of FR-4 board.

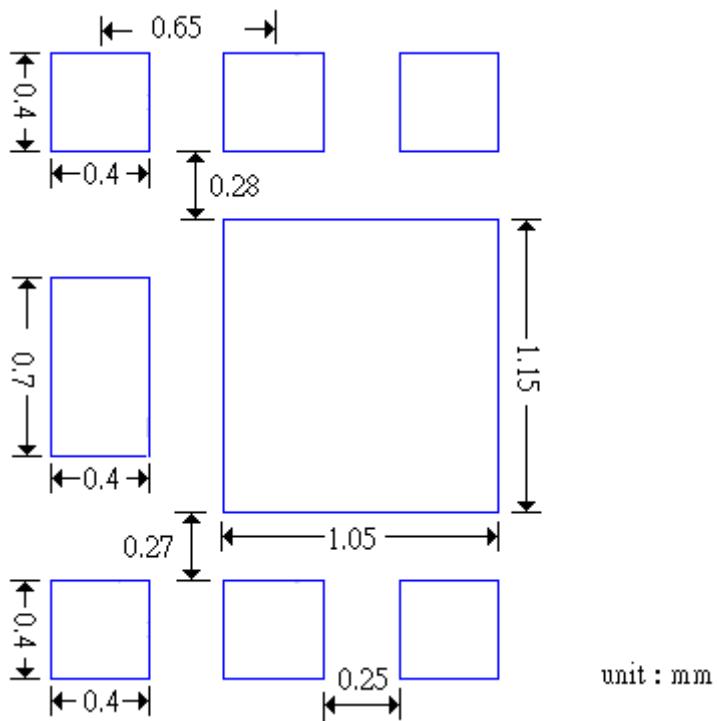
## Electrical Characteristics ( $T_a=25^\circ C$ )

Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
<b>Static</b>						
$BV_{DSS}$	20	-	-	V	$V_{GS}=0V, I_D=250\mu A$	
$V_{GS(th)}$	1	-	2.35	V	$V_{DS}=V_{GS}, I_D=250\mu A$	
$I_{GSS}$	-	-	±100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$	
$IDSS$	-	-	1	μA	$V_{DS}=20V, V_{GS}=0V$	
	-	-	10	μA	$V_{DS}=20V, V_{GS}=0V, T_j=55^\circ C$	
$*R_{DS(ON)}$	-	10.9	14.2	mΩ	$V_{GS}=10V, I_D=8.5A$	
	-	15.3	20		$V_{GS}=4.5V, I_D=6.8A$	
$*G_{FS}$	-	7	-	S	$V_{DS}=5V, I_D=8.5A$	
<b>Dynamic</b>						
$C_{iss}$	-	539	-	pF	$V_{DS}=10V, V_{GS}=0, f=1MHz$	
$C_{oss}$	-	104	-			
$C_{rss}$	-	85	-			
$t_{d(ON)}$	-	10.2	-	ns	$V_{DD}=13V, I_D=8.5A, V_{GS}=4.5V, R_G=1.8\Omega$	
$t_r$	-	21	-			
$t_{d(OFF)}$	-	21.6	-			
$t_f$	-	11.2	-			

$Q_g(V_{GS}=10V)$	-	13	-	nC	$V_{DS}=13V, I_D=8.5A, V_{GS}=10V$
$Q_g(V_{GS}=4.5V)$	-	6.7	-		
$Q_{gs}$	-	1.8	-		
$Q_{gd}$	-	3.0	-		
$R_g$	-	4.7	-		
<b>Source-Drain Diode</b>					
$*V_{SD}$	-	0.87	1.0	V	$V_{GS}=0V, I_S=8.5A$
$*trr$	-	5.9	-	ns	$I_F=8.5A, dI_F/dt=280A/\mu s$
$*Qrr$	-	3.9	-	nC	

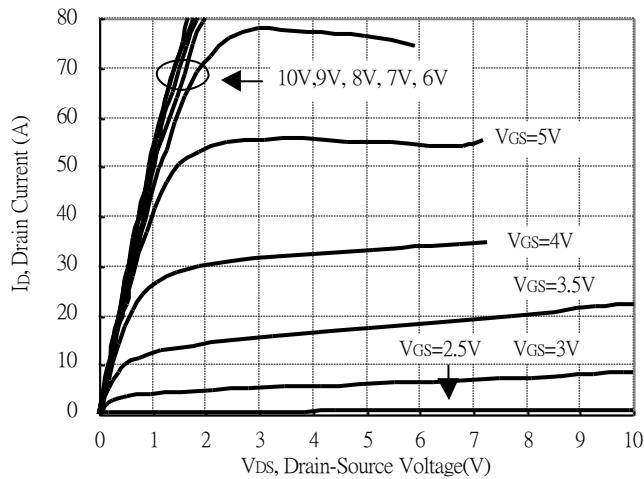
\*Pulse Test : Pulse Width  $\leq$ 300 $\mu$ s, Duty Cycle  $\leq$ 2%

# Recommended Soldering Footprint

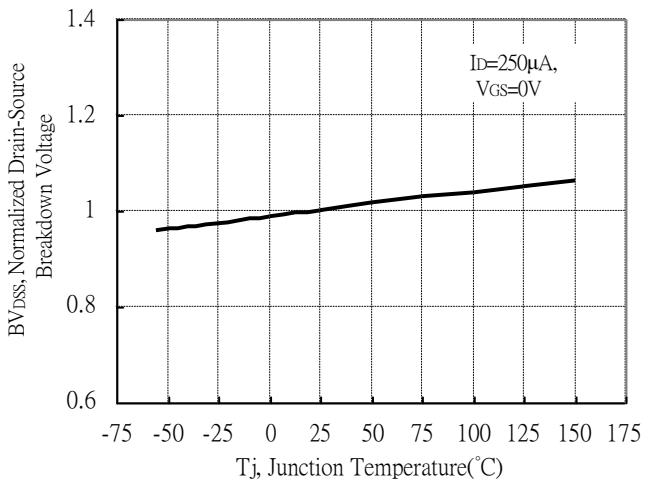


## Typical Characteristics

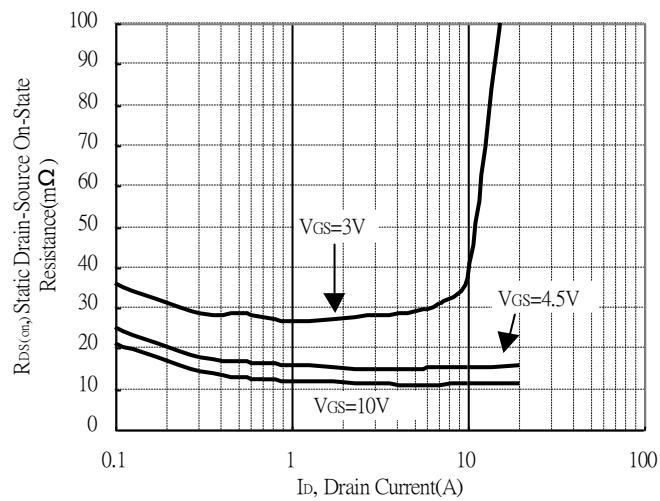
Typical Output Characteristics



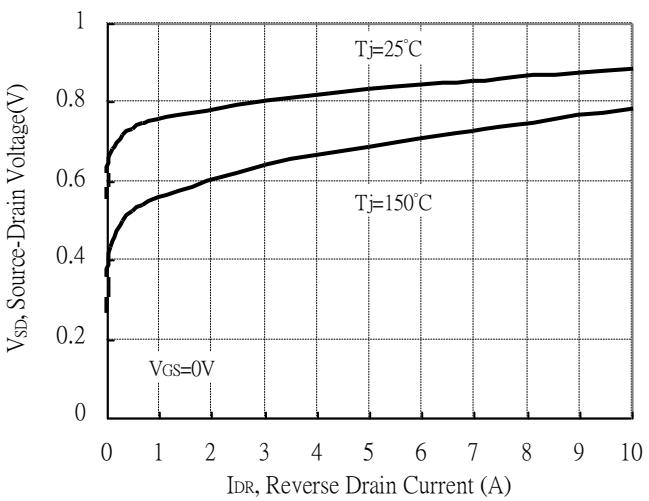
Breakdown Voltage vs Ambient Temperature



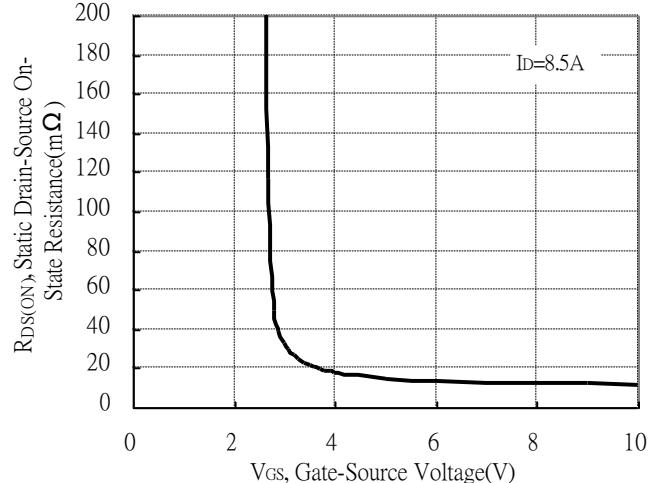
Static Drain-Source On-State resistance vs Drain Current



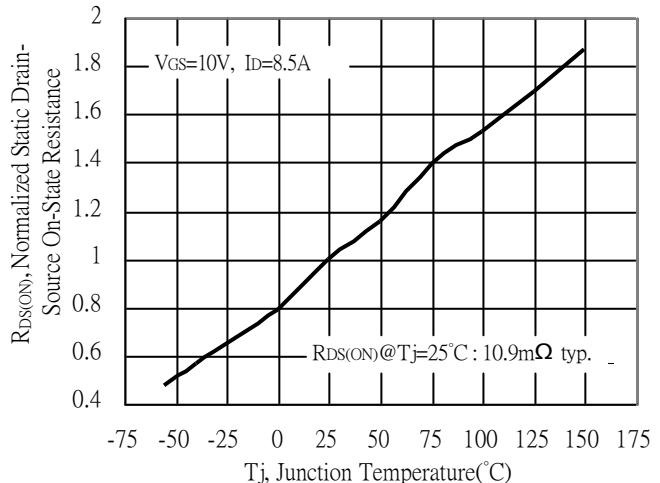
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

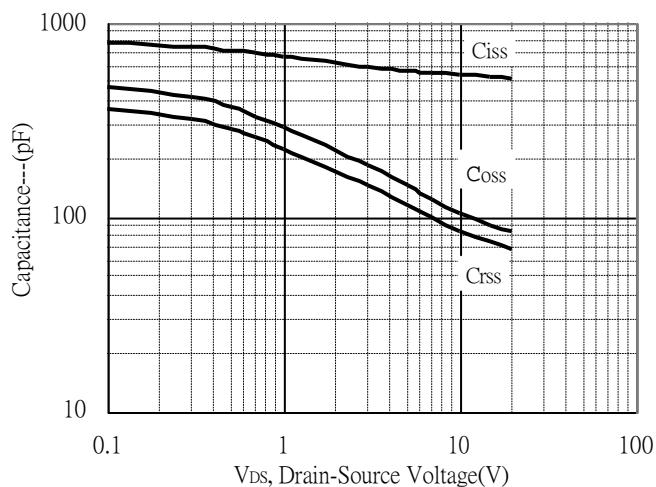


Drain-Source On-State Resistance vs Junction Temperature

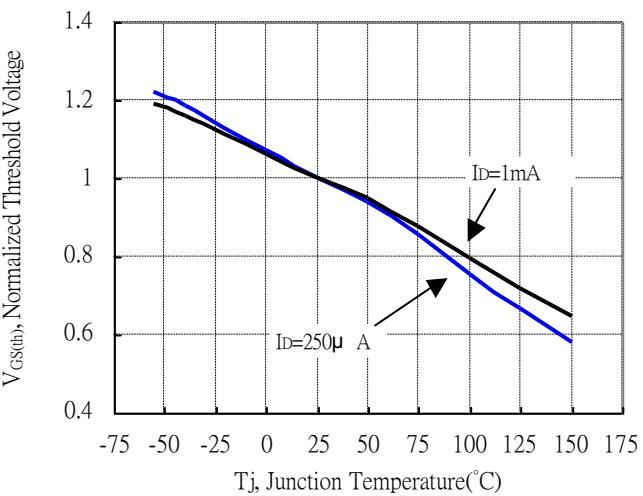


## Typical Characteristics(Cont.)

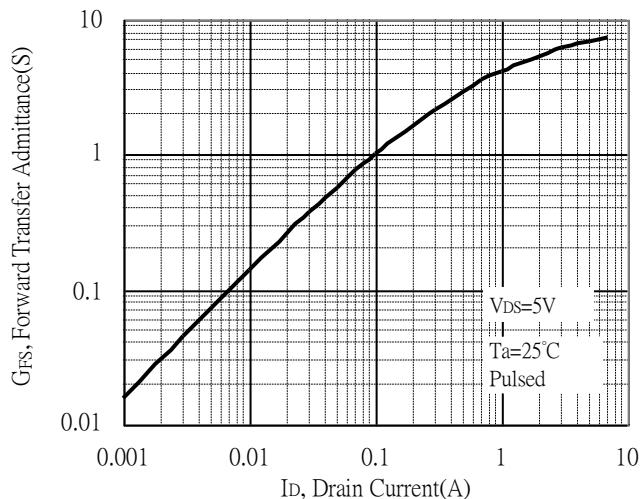
Capacitance vs Drain-to-Source Voltage



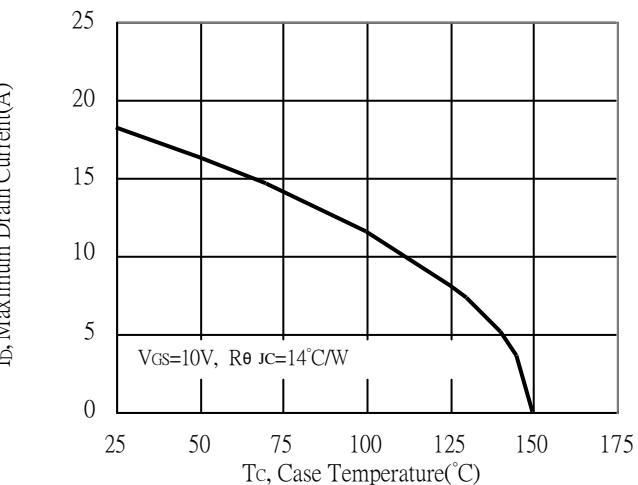
Threshold Voltage vs Junction Temperature



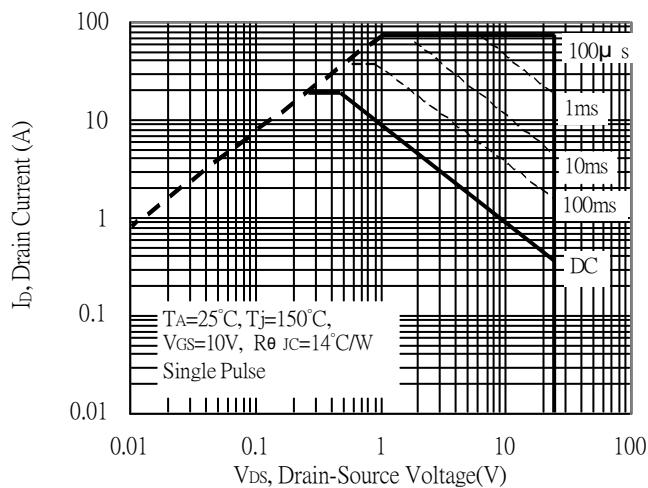
Forward Transfer Admittance vs Drain Current



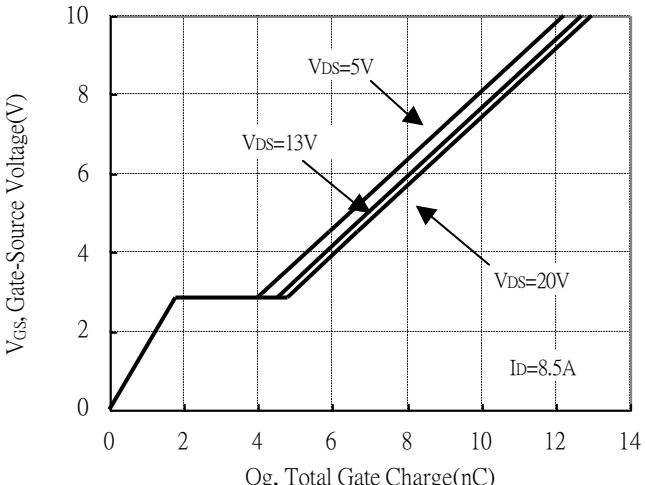
Maximum Drain Current vs Case Temperature



Maximum Safe Operating Area

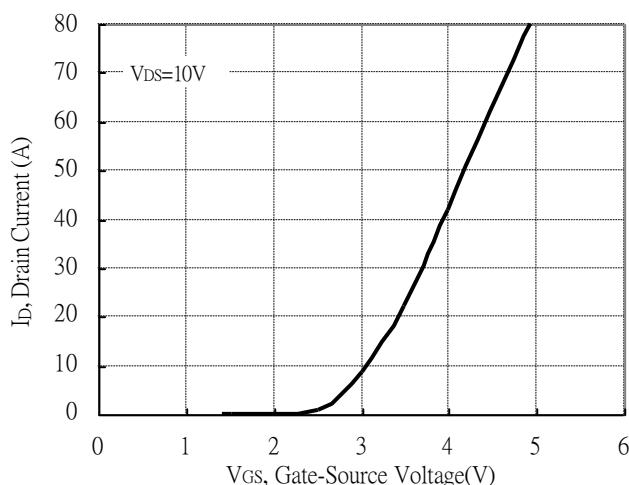


Gate Charge Characteristics

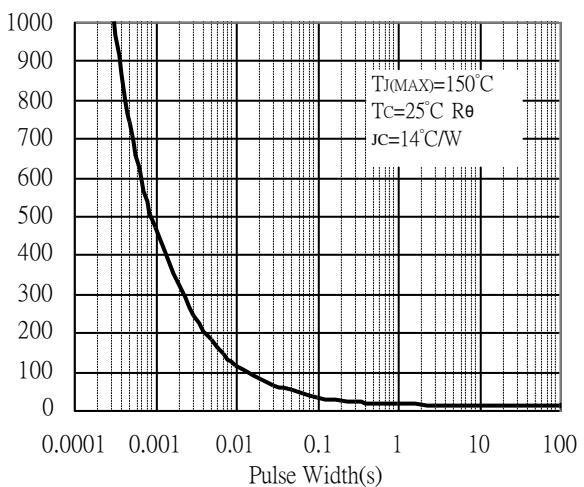


## Typical Characteristics(Cont.)

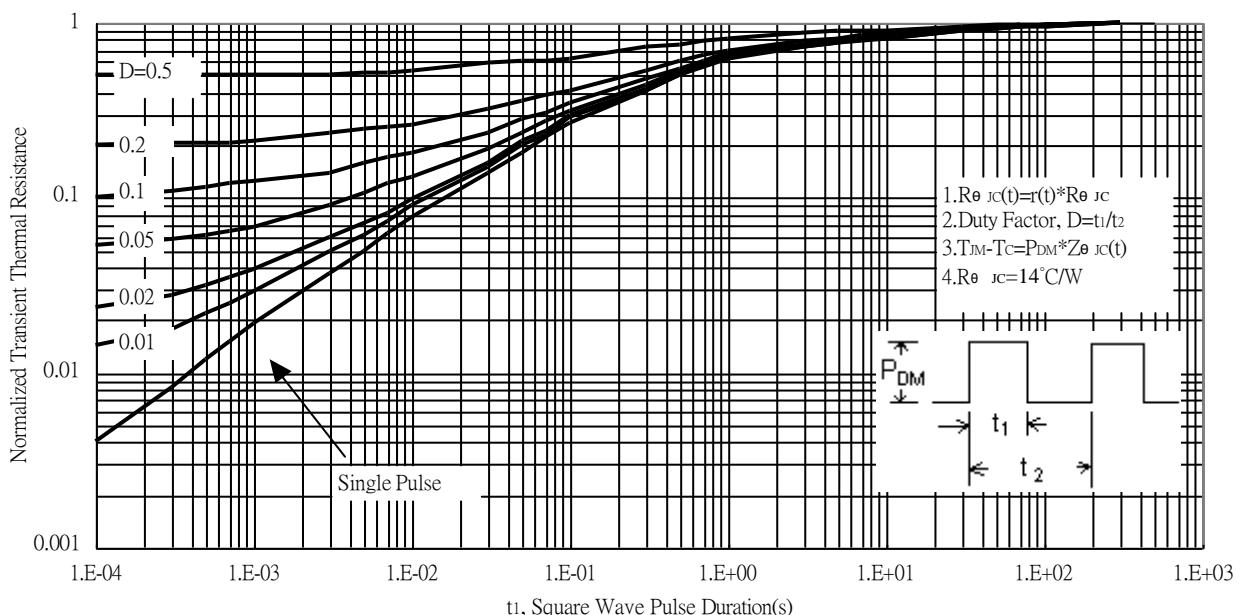
Typical Transfer Characteristics



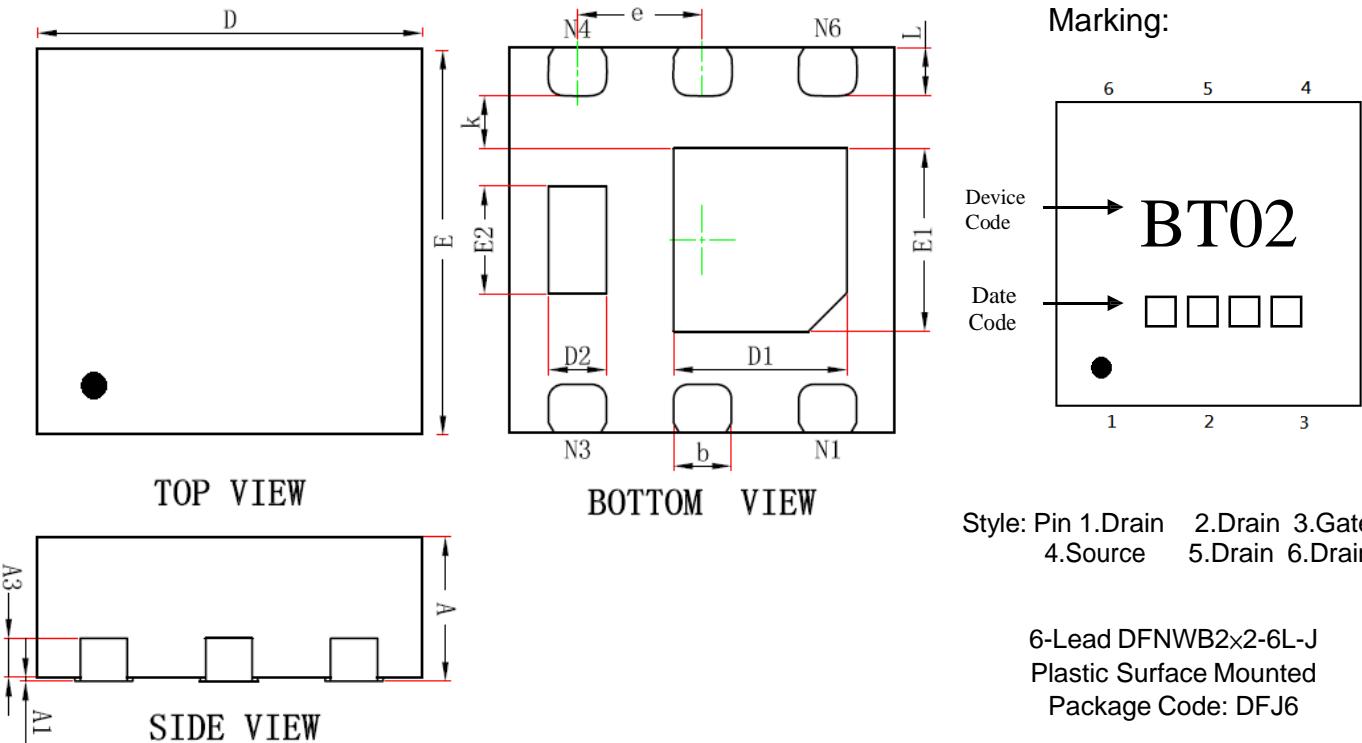
Single Pulse Power Rating, Junction to Case



Transient Thermal Response Curves



### DFNWB2x2-6L-J Dimension



DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031	D2	0.200	0.400	0.008	0.016
A1	0.000	0.050	0.000	0.002	E2	0.460	0.660	0.018	0.026
A3	0.203	REF	0.008	REF	k	0.200	-	0.008	-
D	1.924	2.076	0.076	0.082	b	0.250	0.350	0.010	0.014
E	1.924	2.076	0.076	0.082	e	0.650	TYP	0.026	TYP
D1	0.800	1.000	0.031	0.039	L	0.174	0.326	0.007	0.013
E1	0.850	1.050	0.033	0.041					